

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hideto NAKAGAWA</td> <td>12/10/2007</td> </tr> <tr> <td>Haruhiko MOHRI</td> <td>12/14/2007</td> </tr> <tr> <td>Hirokazu AOYAMA</td> <td>12/12/2007</td> </tr> </tbody> </table>		Name	Execution Date	Hideto NAKAGAWA	12/10/2007	Haruhiko MOHRI	12/14/2007	Hirokazu AOYAMA	12/12/2007
Name	Execution Date								
Hideto NAKAGAWA	12/10/2007								
Haruhiko MOHRI	12/14/2007								
Hirokazu AOYAMA	12/12/2007								
RECEIVING PARTY DATA									
Name:	Daikin Industries, Ltd.								
Street Address:	Umeda Center Building, 4-12,								
Internal Address:	Nakazaki-Nishi 2-chome, Kita-ku								
City:	Osaka-shi, OSAKA								
State/Country:	JAPAN								
Postal Code:	530-8323								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11993446</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11993446				
Property Type	Number								
Application Number:	11993446								
CORRESPONDENCE DATA									
Fax Number:	(202)293-0445								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	2022930444								
Email:	ssaify@giplaw.com								
Correspondent Name:	GLOBAL IP COUNSELORS, LLP								
Address Line 1:	1233 20TH STREET, NW, SUITE 700								
Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20036-2680								
ATTORNEY DOCKET NUMBER:	DK-US050529								
NAME OF SUBMITTER:	John C. Robbins								
Total Attachments: 2 source=DK-US050529_Assignment#page1.tif									

CH \$40.00 11993446

500425689

PATENT
REEL: 020280 FRAME: 0907

ASSIGNMENT

[Executed in Japan]

WHEREAS, Hideto NAKAGAWA, a citizen of Japan with a postal address of c/o DAIKIN INDUSTRIES, LTD., Yodogawa Plant, 1-1, Nishihitotsuya, Settsu-shi, Osaka 566-8585, Japan,
Haruhiko MOHRI, a citizen of Japan with a postal address of c/o DAIKIN INDUSTRIES, LTD., Yodogawa Plant, 1-1, Nishihitotsuya, Settsu-shi, Osaka 566-8585, Japan,
Hirokazu AOYAMA, a citizen of Japan with a postal address of c/o DAIKIN INDUSTRIES, LTD., Yodogawa Plant, 1-1, Nishihitotsuya, Settsu-shi, Osaka 566-8585, Japan,
hereinafter referred to as the Assignor(s), have invented certain new and useful improvements in
SURFACE-MODIFIED NANOFILLER AND POLYMER COMPOSITE MATERIAL

for which the Assignor(s) have executed an Application for United States Letters Patent

(X) executed concurrently herewith
() Serial No. _____ Filed _____

, AND WHEREAS,

DAIKIN INDUSTRIES, LTD.

having its principal place of business at

**Umeda Center Building, 4-12, Nakazaki-Nishi 2-Chome,
Kita-ku, Osaka-shi, Osaka 530-8323, Japan**

(hereinafter referred to as the Assignee), is desirous of acquiring the entire right, title, and interest in and to said invention and said Application and in and to any Letters Patent or Patents, United States or foreign as indicated below, to be obtained therefor and thereon:

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is herewith acknowledged, the Assignor(s) sell, assign, and transfer, unto the Assignee, its successors, legal representatives and assigns, the entire right, title, and interest in the United States of America, and in all foreign countries in, to and under said improvements, and said Application, and all original, divisional, renewal, continuation, substitute, or reissue applications thereof, including the right to sue and recover for any past infringement, and all rights of priority from the filing of said Application; and the Assignor(s) hereby authorize and request the Commissioner of Patents and Trademarks to issue all Letters Patent on said improvements or resulting therefrom to said Assignee herein, as assignee of the entire interest therein, for the sole use and behalf of said Assignee, its successors, and assigns, to the full end of the term or terms for which Letters Patent or Patents may be granted.

Further, the Assignor(s) and their legal representatives, heirs, and assigns do hereby agree and covenant without further remuneration that they will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to them respecting said improvements whenever requested, and will testify in any interferences or other legal proceeding in which any of said applications or Letters Patent may become involved, sign all lawful papers, execute and deliver all divisional, continuing, reissue and other applications for Letters Patent on said improvements and all assignments thereof to said Assignee or its legal representatives, successors, or assigns, make all rightful oaths and generally do everything necessary to assist said Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in the U.S. and said countries, the expenses incident to said applications to be borne and paid by said assignee.

The undersigned hereby grants the firm of **Global IP Counselors, LLP** the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

IN TESTIMONY WHEREOF, the undersigned Assignor(s) has affixed his signature.

This 10 day of December, 2087 Signature Hideto Nakagawa

This 12 day of December, 2007 Signature Haruko Mohri

This 14 day of December, 2007 Signature HARUKO MOHRI

©T:\template dir\Forms - Daikin\Daikin-Assignment.DOC